



Faculty of Manufacturing Engineering

**ELIMINATION OF GOLD TARNISH BY POST DIP AFTER GOLD
PLATING PROCESS IN FLEXIBLE PRINTED CIRCUIT BOARD
MANUFACTURING.**

Umadewi A/P Ganasan

Master of Manufacturing Engineering
(Manufacturing System Engineering)

2018

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PROCESS IN FLEXIBLE PRINTED CIRCUIT BOARD MANUFACTURING.**

UMADEWI A/P GANASAN

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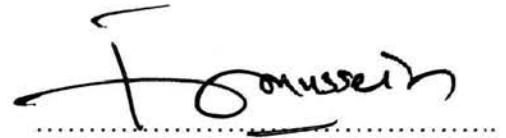
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ABSTRACT

Flexible printed circuits (FPC) industry has high growth rate and high competition. FPC manufacturer should always ensure tighter tolerance to produce the highest quality of output products to their important and fulfill customer's high quality demand. Gold plating is often used in the electronics industry to provide an electrically conductive layer on copper base layers, typically in electrical connectors and printed circuit boards. ENIG provides excellent surface planarity with very good soldering and gold wire bonding. ENIG is now arguably the most used surface finish in the FPC industry due the growth and implementation of the RoHs regulation. There is a weak point in ENIG surface finishing, where RR10 chemical from subsequence process tend to attack the gold layer thereby causing tarnishing of its surface and formation of an oxide and or sulfide layer. Thus, the study help find root cause from subsequence processes that causing gold tarnish. A post dip after gold plating used ABC solution as barrier layer on top of Nickel-Gold layer. The new layer formation from the post dip, was evaluated to ensure that they do not impair the essential surface properties such as contact resistance and solder or bonding functions needed for most connector applications. This study shown RR10 chemical that utilized as a part of stripping process which is end process after ENIG plating tend to oxidise ENIGsurface. The ideal arrangement of handling parameters was observed to dipping time (2 minutes), temperature (27.3°C) and concentration (5.85pH), to accomplish the achieve desired quality failure mode (2 or 3 or 4) and resistance (3-10k Ω). No effect on continuity as gold grains remain bonded and no corroded. The ABC solution coating does not impact properties and functionality of FPCs.

ABSTRAK

Litar bercetak fleksibel industri (FPC) mempunyai kadar pertumbuhan yang tinggi dan persaingan yang tinggi. Pembuatan FPC perlu sentiasa memastikan toleransi yang lebih ketat untuk menghasilkan produk lebih berkualiti untuk memenuhi permintaan pelanggan. Penyaduran emas sering digunakan dalam industri elektronik, sebagai contoh ENIG kini boleh dikatakan penyaduran yang paling banyak digunakan dalam industri FPC kerana pertumbuhan dan pelaksanaannya peraturan Rosh. Terdapat satu titik lemah dalam ENIG kemasan permukaan, di mana bahan kimia daripada proses yang berikutnya cenderung untuk menghakis lapisan emas sekali gus menyebabkan kerosakan permukaan dan pembentukan lapisan oksida dan atau sulfida. Oleh demikian, kajian ini bertujuan mencari punca daripada proses yang berikutnya yang menyebabkan permukaan emas kekuningan atau noda. Satu proses penyaduran selepas penyaduran emas akan membentuk satu lapisan halangan di atas lapisan nikel-emas. Pembentukan lapisan baru, akan diuji untuk memastikan bahawa lapisan baru tidak menjelaskan sifat-sifat permukaan penting seperti rintangan elektrik dan pematrian atau fungsi diperlukan untuk kebanyakan aplikasi penyambungan. Kajian ini menunjukkan bahan kimia RR10 yang digunakan sebagai sebahagian daripada proses pelucutan yang merupakan proses akhir selepas plating ENIG cenderung mengoksida ENIGsurface. Susunan parameter pengendalian yang ideal diperhatikan untuk mencelupkan masa (2 minit), suhu (27.3°C) dan kepekatan (5.85pH), untuk mencapai mod kegagalan kualiti yang diingini (2 atau 3 atau 4) dan rintangan ($3\text{-}10\text{k}\Omega$). Tiada kesan ke atas kesinambungan kerana biji emas kekal terikat dan tidak berkecaci. Lapisan penyelesaian ABC tidak memberi kesan terhadap sifat dan fungsi FPCs.

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TABLE OF CONTENTS

	PAGE
DECLARATION	
APPROVAL	
DEDICATION	
ABSTRACT	i
ABSTRAK	ii
ACKNOWLEDGEMENTS	iii
TABLE OF CONTENTS	iv
LIST OF TABLES	viii
LIST OF FIGURES	x
LIST OF APPENDICES	xii
LIST OF ABBREVIATIONS	xiii
CHAPTER	
1. INTRODUCTION	1
1.0 Company Background	1
1.1 Company Products	3
1.1.1 Single Sided Flex	3
1.1.2 Double Sided Flex	4
1.1.3 Multi-Layer Flex	5
1.1.4 Rigid Flex	7
1.2 Flexible Printed Circuit Manufacturing Process	8
1.3 Background of Study	15
1.4 Problem Statement	17
1.5 Objective of the Study	20
1.6 Scope of the Study	21
1.7 Significance of the Study	21
1.8 Research Planning	22
1.9 Summary	22
2. LITERATURE REVIEW	23
2.0 Introduction of FPC	23
2.1 Classification based on IPC	25

2.2	Major Surface Finish Options for FPC	26
2.2.1	Hot Air Solder Level (HASL OR HAL)	27
2.2.1.1	Fabrication Process	28
2.2.1.2	Advantages and Disadvantages	28
2.2.1.3	Failure Modes	29
2.2.2	Electroless Nickel Immersion Gold (ENIG)	30
2.2.2.1	Fabrication Process	32
2.2.2.2	Advantages and Disadvantages	34
2.2.2.3	Failure Modes	34
2.2.3	Organic Solderability Preservative (OSP)	35
2.2.3.1	Fabrication Process	36
2.2.3.2	Advantages and Disadvantages	38
2.2.3.3	Failure Modes	39
2.3	Gold tarnish	39
2.4	Gold plating as Solderable Coatings	40
2.5	Failure analysis on ENIG surfaces	41
2.5.1	Bad Wetting of ENIG Surface Finish Pads	41
2.6	Anti-tarnish	45
2.6.1	Formation of new copper alloy	45
2.6.2	Anti-tarnishing surface on purple gold substrate	46
2.6.3	Anti-Tarnish Treatment for Copper	48
2.6.4	Tarnish protection of silver jewels by plasma polymer coatings	49
2.7	Reliability test of Printed Circuit Boards	51
2.7.1	Solderability Inspection	51
2.7.2	Solderability Test Methods	53
2.7.3	Wire bonding	54
2.7.4	Electrical Tests	54
2.7.5	Humidity Test	57
2.7.6	Salt spray	57
2.7.6.1	Test procedures	58
2.8	Summary	59
3.	METHODOLOGY	60
3.1	Planning and Activities	60
3.2	Objective 1: To determine root cause of gold tarnish from subsequence processes after gold plating.	63
3.3	Objective 2: To optimise the improvement action	66

3.3.1	Response surface methodology (RSM)	68
3.4	Objective 3: To validate proposed a solution (ABC solution) for gold tarnish without impair the essential gold surface properties	69
3.5	Summary	71
4.	RESULT AND DISCUSSION	72
4.1	Introduction	72
4.2	Analysis on gold tarnish root cause	72
4.2.1	Visual Check	76
4.2.2	Resistance Measurement	81
4.2.3	Wire bonding pull test	83
4.2.4	Summary	90
4.3	Optimization of the Post Dip process.	91
4.3.1	Analysis data for First Response	93
4.3.1.1	Sequential Model Sum of Squares	93
4.3.1.2	Lack of Fit Tests	93
4.3.1.3	Model Summary Statistics	94
4.3.1.4	ANOVA for Response Surface Quadratic Model	94
4.3.2	Analysis data for Second Response	99
4.3.2.1	Sequential Model Sum of Squares	99
4.3.2.2	Lack of Fit Tests	99
4.3.2.3	Model Summary Statistics	100
4.3.2.4	ANOVA for Response Surface Quadratic Model	101
4.3.3	Analysis data for Optimization	105
4.3.3.1	Numerical Optimization	106
4.3.3.2	Graphical Optimization	106
4.3.3.3	Points Prediction	107
4.3.4	Summary	107
4.4	To validate proposed a solution	109
4.4.1	Visual Check and Resistance Measurement	110
4.4.2	Wire Bonding Pull Test	111
4.4.3	Salt Spray Test	112
4.4.4	Summary	113
5.	CONCLUSION AND RECOMMENDATION	116
5.1	Conclusion	116

5.1.1	Objective 1 - To determine root cause of gold tarnish from subsequence processes after gold plating.	117
5.1.2	Objective 2 - To optimise the improvement action.	118
5.1.3	Objective 3 - To validate ABC solution for gold tarnish without impair the essential gold surface properties.	118
5.2	Overview of the improvement	119
5.3	Recommendation	120
	REFERENCES	121
	APPENDICES	128

LIST OF TABLES

TABLE	TITLE	PAGE
2.1	HASL advantages and disadvantages	29
2.2	Process flow of ENIG	33
2.3	ENIG advantages and disadvantages	34
2.4	Process Flow for Organic Solderability Preservative	37
2.5	Comparing the Advantages and Disadvantages of OSP	38
2.6	Test condition	58
3.1	Three process factors	68
3.2	Three-level Box-Behnken design	68
4.1	Summary of Fishbone Analysis	74
4.2	Visual checking for samples 1-5 immersed in AD48	77
4.3	Visual checking for samples 6-10 immersed in AD48	78
4.4	Visual checking for samples 1-5 immersed in RR10	79
4.5	Visual checking for samples 6-10 immersed in RR10	80
4.6	Resistance value before after for samples immersed in AD48 and RR10	82
4.7	Wire pull test data	89
4.8	Results of the trial run	92
4.9	Sequential Model Sum of Squares	93
4.10	Lack of Fit Tests	93

4.11	Model Summary Statistics	94
4.12	Analysis of variance table (Partial sum of squares)-1	94
4.13	Analysis of variance (Partial Sum of squares)-2	95
4.14	Adeq Precision	95
4.15	Diagnostics Case Statistics	97
4.16	Sequential Model Sum of Squares	99
4.17	Lack of Fit Tests	100
4.18	Model Summary Statistics	100
4.19	Analysis of variance table (Partial sum of squares)-1	101
4.20	Analysis of variance (Partial Sum of squares)-2	101
4.21	Adeq Precision	102
4.22	Diagnostics Case Statistics	103
4.23	Design Summary	105
4.24	Ten solutions	106
4.25	Visual check and resistance measurement result	111
4.26	Visual check and pull strength result	112
4.27	Salt spray test result for Control Sample and Sample X	113

LIST OF FIGURES

FIGURE	TITLE	PAGE
1.1	MFS Technology Sdn Bhd	3
1.2	Single sided flex	4
1.3	Double sided flex	5
1.4	Multilayer flex	6
1.5	Rigid flex	7
1.6	Generic process flow diagram for flex manufacture	14
1.7	Pareto chart	18
1.8	Gold tarnish by Surface finishing typ	19
1.9	Gold tarnish by flex type	19
2.1	a) HASL equipment b) surface electron micrograph (SEM)	30
2.2	SEM image of the nickel plating of bare PTH pad	42
2.3	SEM image (a) and EDS spectrum (b) of the surface of the bad wetting pad	42
2.4	XPS depth profile of the bare PTH pad	43
2.5	SEM image of cross-section morphology of the bare PTH pad	44
2.6	PTH pad on PCB after the solderability test	45
2.7	The microscopy images of matte PG and glossy PG	48
2.8	“Wetted” solder joint	53
2.9	Non- “wetted” solder joint	53
2.10	General principle of noncontact electrical testing	56
2.11	Principle of noncontact testing for open circuits	56

2.12	Principle of noncontact testing for short-circuits	57
3.1	Overall methodology for conducting the project	62
3.2	Process Flow for first objective	65
3.3	Process Flow for second objective	67
3.4	Process Flow for third objective	70
4.1	Fishbone diagram	73
4.2	5xWhy analysis	74
4.3	Measuring system: (a) photograph of the system and (b) schematic of the four-point probe method.	82
4.4	Resistance measurement	83
4.5	Bond pull tester	84
4.6	Wire pull test	85
4.7	Pull test acceptance criteria according to DVS 2811	85
4.8	Failure mode grade 4	88
4.9	Failure mode grade 3	88
4.10	Failure mode grade 2	88
4.11	Wire pull force data analysis	89
4.12	Failure mode analysis	90
4.13	Normal plot of residuals (Design Expert)	98
4.14	3D surface interactions between dipping time and temperature	98
4.15	Normal plot of residuals (Design Expert)	104
4.16	3D surface interactions between dipping time and temperature	104
4.17	Over-lay Plot (Design Expert)	106
4.18	Prediction Points	107
4.19	a) FPC structure before coated with ABC solution b) FPC structure after coated with ABC solution	109
4.20	FESEM micrography for a) Control Sample b) Sample X	110
5.1	Pareto chart (MFS Quality ,2018)	117

LIST OF APPENDICES

APPENDIX	TITLE	PAGE
A	Project Gantt Chart	126
B	ENIG Process Start-up Checklist	127
C	Production Record Book	128

LIST OF ABBREVIATIONS

PCB	-	Printed Circuit Board
FPC	-	Flexible Printed Circuit
HDI	-	High-Density Interconnect
Cd	-	Cadmium
Hg	-	Mercury
Pb	-	Lead
LCD	-	Liquid crystal display
DFM	-	Design for Manufacturing
UV	-	Ultraviolet
HASL	-	Hot Air Soldering Leveling
OSP	-	Organic Solderability Preservative
ENEPiG	-	Electroless Nickel Electroless Palladium Immersion Gold
ENiG	-	Electroless Nickel Immersion Gold
Ni	-	Nickel

RSM	-	Response Surface Methods
SEM	-	Scanning Electron Microscope
FFC	-	Flexible Flat Cables
PET	-	Polyethylene Terephthalate
LCD	-	Liquid crystal display
OLED	-	Organic light-emitting diodes
IPC	-	Institute for Printed Circuits
EN	-	electroless nickel
XRF	-	x-ray fluorescence
PTH	-	Plated Through Hole
OM	-	Optical Microscope
EDS	-	Energy Dispersive Spectrometer
XPS	-	X-ray photoelectric spectroscopy
PG	-	Purple gold
EDX	-	Energy Dispersive X-Ray
OEM	-	Original Equipment Manufacturer
DI	-	Deionized
UTS	-	Ultimate Tensile Strength
BBD	-	Box Behnken design

CHAPTER 1

INTRODUCTION

This chapter contains the background of the study and background of company, MFS Technology Sdn. Bhd, problem statement, aim and objectives, and scope of the study. The significance and the expected outcomes of this study are likewise presented at the end of this chapter.

1.0 Company Background

MFS Technology was incorporated in Singapore in the year 1989. The company has first changed the name to MFS Technology Limited which is a holding company for cooperative company in 3 countries such as China, Singapore, and Malaysia. Currently, MFS Technology (S) Pte Ltd is a headquarter office which is in Wearnes Building, Central North of Singapore. In China, there are 2 MFS manufacturing plant for FPC and PCB at Hunan. While there is also another one factory which is in Malacca, Malaysia, namely as MFS Technology (M) Sdn Bhd which can be seen in Figure 1.1.

The basis business is in the manufacture, design, and distribution of printed circuit board (PCB), flexible printed circuit (FPC), rigid flex, turnkey component assembly services and module level integration as strengthen their vertical supply chain to provide a one-stop solution. The company's strategically located manufacturing sites and a customer-centric culture ensures MFS connects with worldwide system of enhanced customer base rapidly. Besides that, it is the vital to meet customers' expectations.

In Malacca, MFS Technology (M) Sdn Bhd specialized in high volume single, ultra-high-density interconnect (HDI) flex, double, rigid flex and multilayer flex. This company has been complied with the ISO 9001, TS16949, ISO 14001, OHSAS 18001 and ISO 13485 requirements.

Furthermore, MFS continues improvement and compliances with legal as well as other requirement related to the environmental aspects. From the company, MFS have been implemented and confined the utilization of hazardous substance (ROHS) such as Cadmium (Cd), Mercury (Hg), Lead (Pb), and others hazardous materials (MFS,2016). Currently, flexible printed circuit (FPC) products of MFS Technology can be applied to various variety fields such as communication smartphones, automotive, medical, and data storage (MFS,2016).



Figure 1.1 MFS Technology Sdn Bhd (Melaka)

1.1 Company Products

MFS has the product design and manufacturing capabilities to provide a comprehensive range of PCB, FPCs, Rigid flex and assembly with personalized features to meet customers' needs for flexible services, and responsive within a short lead time.

Below sub-sections are the brief explanations on company products.

1.1.1 Single Sided Flex

A single layer flex circuit as in Figure 1.2, is the most fundamental and comprises of a flexible polyimide film laminated to a thin sheet of copper based on Roy (2017). The copper layer is then chemically etched to create a circuit